

INTERNATIONAL STANDARD

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Test methods for electrical materials, printed boards and other interconnection structures and assemblies -

Part 3-302: Detection of plating defects in unpopulated circuit boards by computed tomography (CT)

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles -

Partie 3-302: Détection des défauts de métallisation dans les cartes de circuits imprimés nus par tomographie informatisée (TI)



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Document Preview

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**Test methods for electrical materials, printed boards
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Part 3-302: Detection of plating defects in unpopulated
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Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.